

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| APPLICANT: | C. Huang | CONF. NO.: | 5161 |
| U.S. SERIAL NO.: | 10/787,269 | GROUP: | 2814 |
| FILED: | February 25, 2004 | EXAMINER: | P. Cao |
| FOR: | SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING STRUCTURE | | |

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicant is in receipt of the Office Action dated January 30, 2007 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.